

Amendments to the Claims:

The following listing of claims will replace all prior versions, and listings, of claims in the application:

1. (Previously Presented) A surface mounting type planar magnetic device wherein a lower ferrite magnetic film is formed on a substrate; a planar coil is formed on said lower ferrite magnetic film; an upper ferrite magnetic film having an opening above a terminal portion of said planar coil is formed; and an external electrode conductive with said planar coil terminal portion is formed, wherein the planar coil is composed of a Cu conductor and formed by electro plating with two-layered film comprising a film composed of a metal selected from Nb, Ta, Mo and W or alloy constituted of two or more thereof and Cu film as plating foundation.

2. (Previously Presented) A surface mounting type planar magnetic device wherein a lower ferrite magnetic film is formed on a substrate; a planar coil is formed on said lower ferrite magnetic film; an upper ferrite magnetic film having an opening above a terminal portion of said planar coil is formed; and an external electrode conductive with said planar coil terminal portion is formed, wherein average composition of the upper ferrite magnetic film and the lower ferrite magnetic film is Fe_2O_3 : 40 to 50 mol%, ZnO : 15 to 35 mol%, CuO : 0 to 20 mol%, Bi_2O_3 : 0 to 10 mol% while remainder thereof is composed of NiO and unavoidable impurity.

3. (Currently Amended) A production method of a surface mounting type planar magnetic device wherein upon production of a surface mounting type planar magnetic device wherein a lower ferrite magnetic film is formed on a substrate; a planar coil is formed on said lower ferrite magnetic film; an upper ferrite magnetic film having an opening above a terminal portion of said planar coil is formed; and an external electrode conductive with said planar coil terminal portion is formed, wherein upon production of the surface mounting type

planar magnetic device, a planar coil terminal is subjected to ~~surface treatment~~light etching with acid and washing with organic solvent prior to coupling of a planar coil terminal portion and an external electrode.

4. (Previously Presented) A production method of a surface mounting type planar magnetic device wherein upon production of a surface mounting type planar magnetic device wherein a lower ferrite magnetic film is formed on a substrate; a planar coil is formed on said lower ferrite magnetic film; an upper ferrite magnetic film having an opening above a terminal portion of said planar coil is formed; and an external electrode conductive with said planar coil terminal portion is formed, wherein upon production of the surface mounting type planar magnetic device, an upper ferrite magnetic film is baked at a temperature of 900°C or more to 1050°C or less in the atmosphere of less than 1 vol.% in oxygen concentration after said upper ferrite magnetic film is applied.

5. (New) A surface mounting type planar magnetic device comprised of upper ferrite magnetic film, lower ferrite magnetic film and a planar coil interposed therebetween, in which an opening is formed in said upper ferrite magnetic film above a planar coil terminal portion and an external electrode conductive with said coil terminal portion through said opening is formed on said upper ferrite magnetic film, wherein the planar coil is composed of a Cu conductor formed by electro plating with two-layered film comprising a film composed of a metal selected from Nb, Ta, Mo and W or alloy constituted of two or more thereof and Cu film as plating foundation.

6. (New) A surface mounting type planar magnetic device comprised of upper ferrite magnetic film, lower ferrite magnetic film and a planar coil interposed therebetween, in which an opening is formed in said upper ferrite magnetic film above a planar coil terminal portion and an external electrode conductive with said coil terminal portion through said opening is formed on said upper ferrite magnetic film, wherein average composition of the

upper ferrite magnetic film and the lower ferrite magnetic film is Fe_2O_3 ; 40 to 50 mol%, ZnO : 15 to 35 mol%, CuO : 0 to 20 mol%, Bi_2O_3 : 0 to 10 mol% while remainder thereof is composed of NiO and unavoidable impurity.

7. (New) A production method of a surface mounting type planar magnetic device comprised of upper ferrite magnetic film, lower ferrite magnetic film and a planar coil interposed therebetween, in which an opening is formed in said upper ferrite magnetic film above a planar coil terminal portion and an external electrode conductive with said coil terminal portion through said opening is formed on said upper ferrite magnetic film, wherein upon production of the surface mounting type planar magnetic device, a planar coil terminal is subjected to surface treatment prior to coupling of a planar coil terminal portion and an external electrode.

8. (New) A production method of a surface mounting type planar magnetic device comprised of upper ferrite magnetic film, lower ferrite magnetic film and a planar coil interposed therebetween, in which an opening is formed in said upper ferrite magnetic film above a planar coil terminal portion and an external electrode conductive with said coil terminal portion through said opening is formed on said upper ferrite magnetic film, wherein upon production of the surface mounting type planar magnetic device, an upper ferrite magnetic film is baked at a temperature of 900°C or more to 1050°C or less in the atmosphere of less than 1 vol.% in oxygen concentration after said upper ferrite magnetic film is applied.